



Product Change Notification

Change Notification #: 115950 - 00
Change Title: Intel® NUC Board NUC5i3MYBE,
Intel® NUC Board NUC5i5MYBE,
Intel® NUC Kit NUC5i3MYHE,
Intel® NUC Kit NUC5i5MYHE,
PCN 115950-00, Product Design,
Documentation,
Firmware Update and Flyer Update in Kit
SKUs
Date of Publication: November 29, 2017

Key Characteristics of the Change:

Product Design, Documentation

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 18, 2017
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Description of Change to the Customer:

The Intel® NUC Board and Intel® NUC Kit SKUs listed in the products affected table below will have the following changes.

1. The Trusted Platform Module (TPM 2.0) SLB 9665 firmware will be updated from version 5.4 to 5.62 to address CVE-2017-15361 (<http://cve.mitre.org/cgi-bin/cvename.cgi?name=CVE-2017-15361>).
2. For NUC5i3MYHE and NUC5i5MYHE kits the attention flyer will be updated.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality or reliability implications to our customers.

Milestone dates are estimates and subject to change based on business and operational conditions.

Customer can expect to receive mixed inventory until current inventory levels are depleted.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change SA	Pre Change AA	Post Change TA	Post Change SA	Post Change AA
BLKNUC5I5MYHE	938688	H47799-107	H47796-208	H47797-208	H47799-108	H47796-209	H47797-209
BLKNUC5I5MYBE	938713			H47797-208			H47797-209
BLKNUC5I3MYHE	938715	H47786-107	H52443-207	H47781-207	H47786-108	H52443-208	H47781-208
BLKNUC5I3MYBE	938717			H47781-207			H47781-208

PCN Revision History:

Date of Revision:

November 29, 2017

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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